

FEATURES

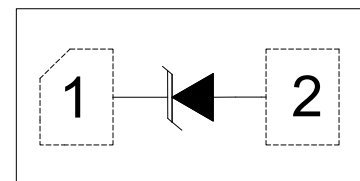
- ✧ Protects one line I/O or power line
- ✧ Low clamping voltage
- ✧ Low leakage current
- ✧ Ultra low capacitance: 100pF(max)
- ✧ RoHS compliant



DFN1006-2L(Bottom view)

MAIN APPLICATIONS

- ✧ USB 2.0 power and data line protection
- ✧ High speed data line
- ✧ LAN equipment
- ✧ Digital visual interface (DVI)
- ✧ Video



Pin Configuration(Top view)

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (air), $\pm 30\text{kV}$ (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lightning) 10A (8/20 μs)

MECHANICAL CHARACTERISTICS

- ✧ DFN1006-2L package
- ✧ Molding compound flammability rating : UL 94V-0
- ✧ Quantity per reel : 10,000pcs
- ✧ Lead finish : lead free
- ✧ Marking code: P5

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20 μs waveform	P _{PP}	150	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	+/- 30	kV
ESD per IEC 61000-4-2 (Contact)		+/- 30	
Lead soldering temperature	T _L	260 (10 sec.)	°C
Operating junction temperature range	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (TA=25°C)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V _{RWM}				5.0	V
Reverse breakdown voltage	V _{BR}	I _T =1mA Pin2 to 1	6.0		8.0	V
Reverse leakage current	I _R	V _{RWM} =5V		0.01	0.1	μA
Forward voltage	V _F	I _F =15mA		0.8	1.1	V
Peak pulse current	I _{PP}	t _P =8/20μs			10	A
Clamping voltage	V _C	I _{PP} =1A, t _P =8/20μs		8.5	10	V
		I _{PP} =10A, t _P =8/20μs		12	15	
Junction capacitance	C _J	V _{RWM} =0V, f=1MHz		75	100	pF

RATINGS AND V-I CHARACTERISTICS CURVES (TA=25°C, unless otherwise noted)

FIG.1:V- I curve characteristics (Uni-directional)

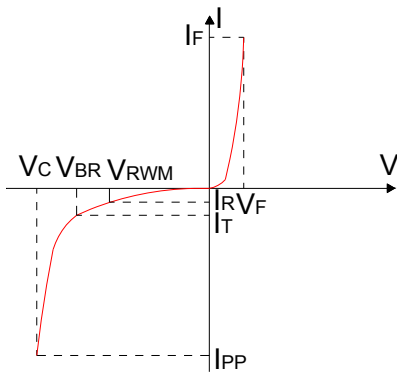


FIG.2: Pulse waveform (8/20μs)

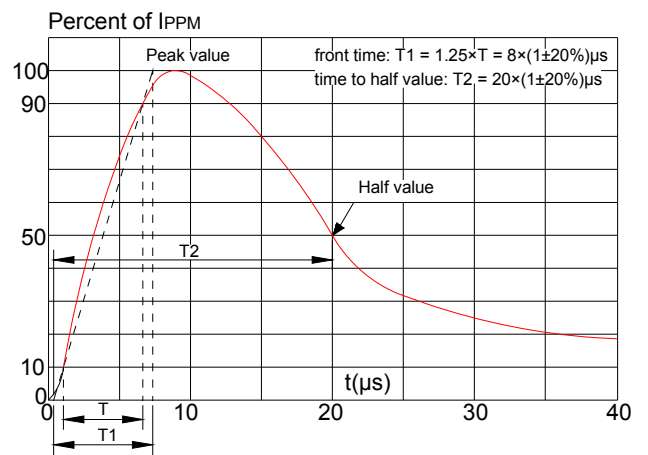


FIG.3: Pulse derating curve

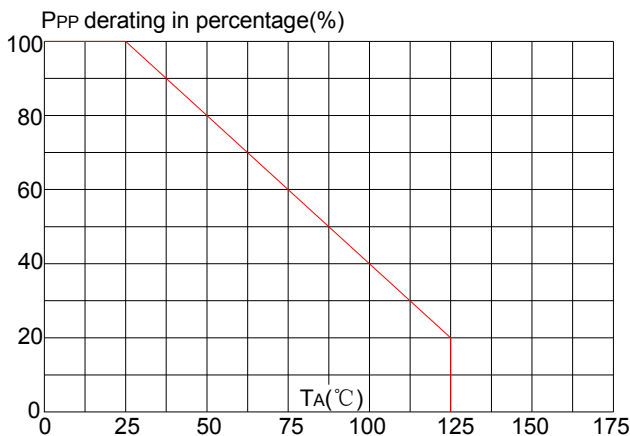
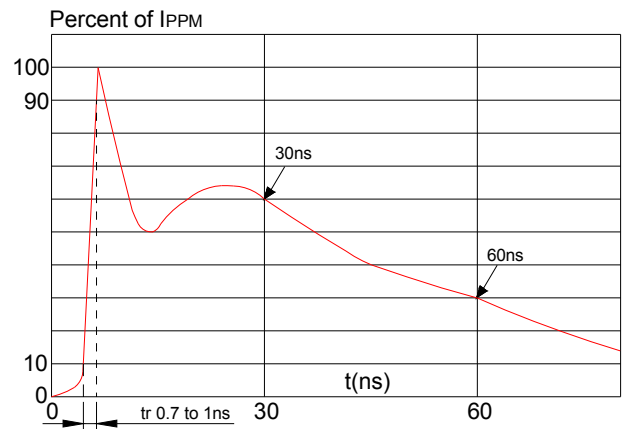
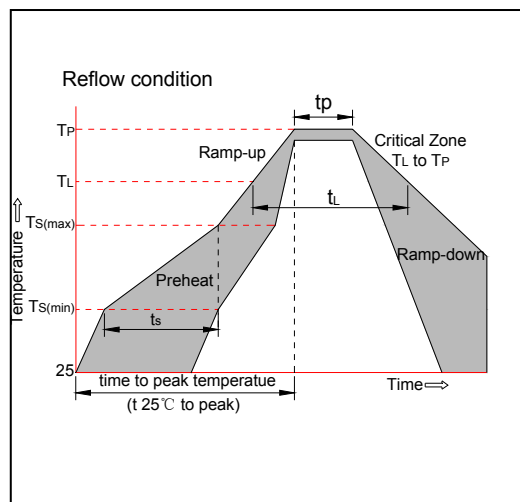


FIG.4: ESD clamping (30KV contact)

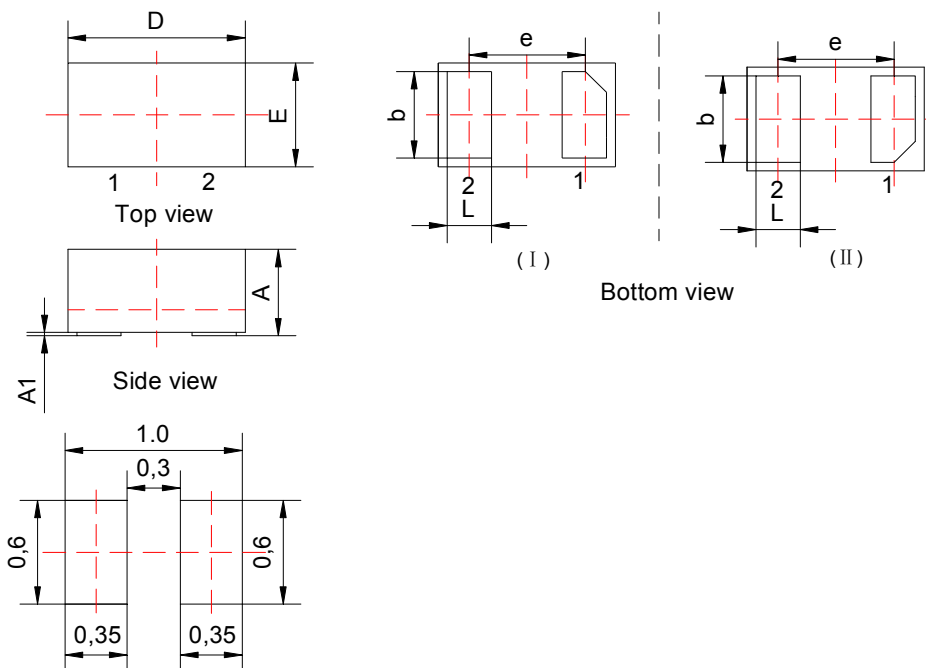


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



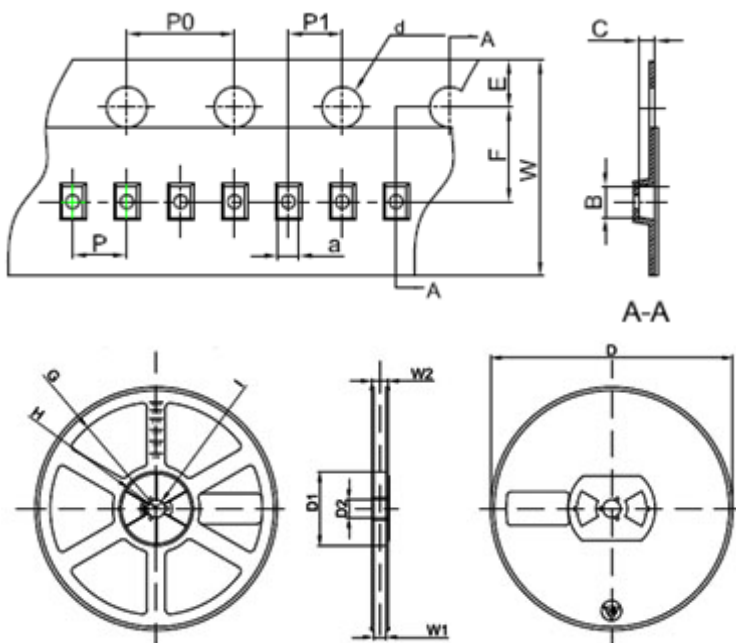
PACKAGE MECHANICAL DATA



Recommended soldering footprint(mm)

Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.50	0.55	0.016	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65BSC			0.026BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.20	0.25	0.30	0.008	0.010	0.012

TAPE AND REEL INFORMATION-DFN1006-2L



Symbol	Millimeter	Inches
	Typ.	Typ.
a	0.66	0.026
B	1.15	0.045
C	0.66	0.026
d	Φ1.50	Φ0.059
E	1.75	0.069
F	3.50	0.138
P0	4.00	0.157
P	2.00	0.079
P1	2.00	0.079
W	8.00	0.315
D	Φ178	Φ7.008
D1	54.40	2.142
D2	13.00	0.512
G	R78.00	R3.071
H	R25.60	R1.008
I	R6.50	R0.256
W1	9.50	0.374
W2	12.30	0.484

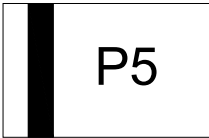
Packaging Description:

DFN1006-2L parts are shipped in tape. The carrier tape is made from a dissipative(carbon filled) polycarbonate resin. The cover tape is a multilayer film(heat activated adhesive in nature)primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 10,000units per 7" or 17.8cm diameter reel. The reels are clear in color and made of polystyrene plastic(anti-static coated).

ORDERING INFORMATION

OUTLINE	Package	Reel Size	Quantity Per Reel
TAPING	DFN1006-2L	7 Inch	10,000 pcs

MARKING CODE

Part Number	Marking Code
JEU05DF	

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